NASCENTechnology, Inc. has developed a series of high temperature, RoHS compliant inductors using low temperature co-fired ceramic (LTCC) ferrite usable to 300°C that feature low profile, rugged packaging, and self shielding characteristics. See individual data sheets for part dimensions.

**Electrical Parameters at 25 °C unless otherwise noted**

<table>
<thead>
<tr>
<th>Part No.</th>
<th>No Load Inductance†</th>
<th>100 mA Inductance</th>
<th>100 mA Tolerance</th>
<th>Nominal DC Resistance ohms</th>
<th>Rated Current††</th>
<th>Saturation Current* mA</th>
</tr>
</thead>
<tbody>
<tr>
<td>85081</td>
<td>10.7</td>
<td>10.7</td>
<td>20%</td>
<td>0.28</td>
<td>-</td>
<td>950</td>
</tr>
<tr>
<td>85082</td>
<td>52</td>
<td>52</td>
<td>20%</td>
<td>1.4</td>
<td>-</td>
<td>350</td>
</tr>
<tr>
<td>85083</td>
<td>91</td>
<td>91</td>
<td>20%</td>
<td>2.75</td>
<td>-</td>
<td>290</td>
</tr>
</tbody>
</table>

† Tolerance for no load inductance is ±25%
†† Current will cause a 35 °C temperature rise over ambient (measured 20 to 55 °C)
* Saturation Current is the current that results in a 35% decrease in inductance over the 100 mA Inductance.

Thickness varies by part; the range is 0.032-0.100 in [0.8-2.54 mm]

Common termination options (please add option to the end of the part number when inquiring):
- A0 Thick film AgPt with side terminations, solderable, compliant to MIL-PRF-123D Appendix B
- C0 Thick film Au, Au wirebonding
- D0 Au over Ni, solderable, compliant to MIL-PRF-123D Appendix B
- D1 Au over Ni, Al wirebonding
- F0 Thick film AgPt without side terminations, solderable, compliant to MIL-PRF-123D Appendix B